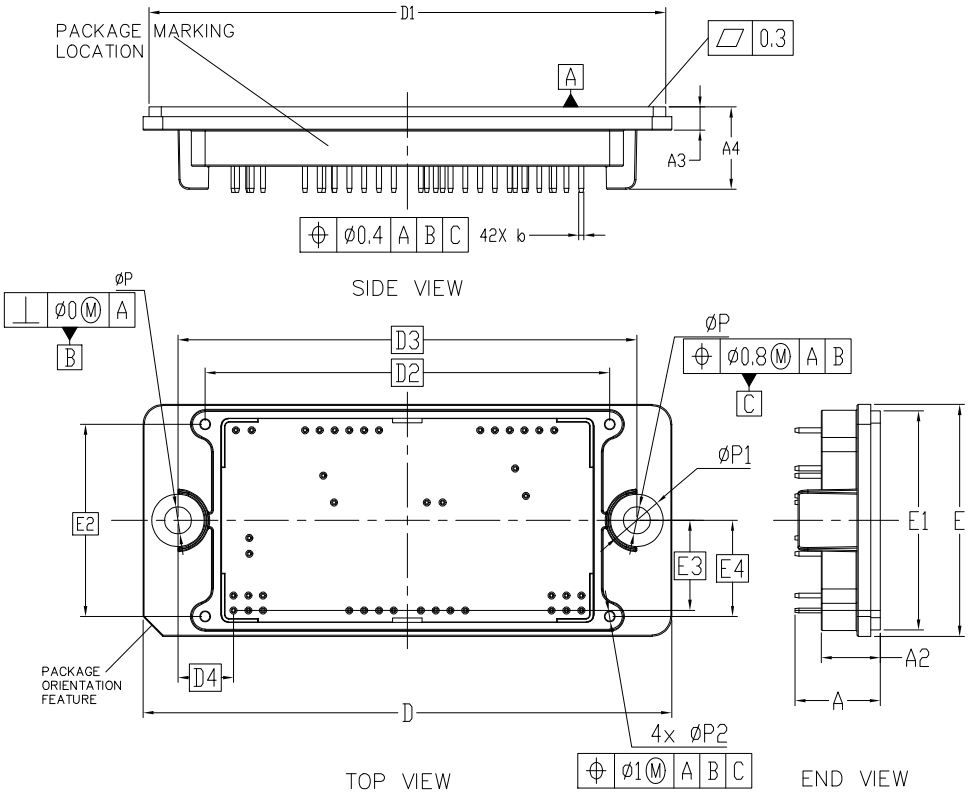


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NOTES:
1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5−2018.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. PIN POSITION TOLERANCE IS ± 0.4MM.
4. PACKAGE MARKING IS LOCATED ON THE SIDE OPPOSITE THE PACKAGE ORIENTATION FEATURE.
5. THE PINS ARE SN−NI PLATED SOLDER PIN.



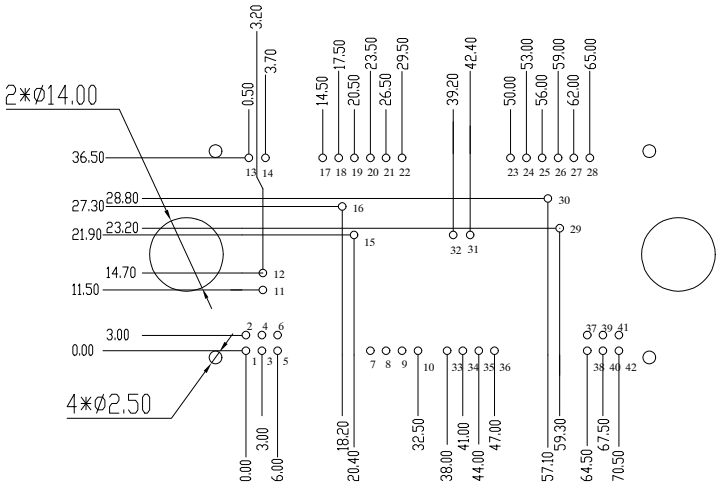
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	16.92	17.32	17.72
A2	11.70	12.00	12.30
A3	4.40	4.70	5.00
A4	16.40	16.70	17.00
b	0.95	1.00	1.05
D	106.90	107.20	107.50
D1	104.45	104.75	105.05
D2	82.00 BSC		
D3	93.00 BSC		
D4	11.25 BSC		
E	46.70	47.00	47.30
E1	44.10	44.40	44.70
E2	39.00 BSC		
E3	18.25 BSC		
E4	19.50 BSC		
P	5.40	5.50	5.60
P1	10.60	10.70	10.80
P2	1.80	2.00	2.20

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RECOMMENDED
MOUNTING PATTERN

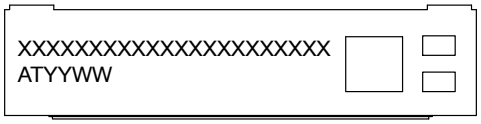
* For additional Information on our Pb−Free strategy and soldering details, please download the Onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTE 2:

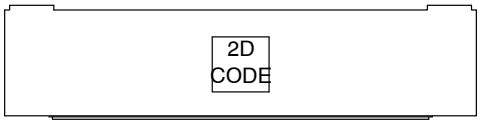
Pin Table

Pin	X	Y	Pin	X	Y	Pin	X	Y
1	0	0	15	20.4	21.9	29	59.3	23.2
2	0	3	16	18.2	27.3	30	57.1	28.8
3	3	0	17	14.5	36.5	31	42.4	21.9
4	3	3	18	17.5	36.5	32	39.2	21.9
5	6	0	19	20.5	36.5	33	38	0
6	6	3	20	23.5	36.5	34	41	0
7	23.5	0	21	26.5	36.5	35	44	0
8	26.5	0	22	29.5	36.5	36	47	0
9	29.5	0	23	50	36.5	37	64.5	3
10	32.5	0	24	53	36.5	38	64.5	0
11	3.2	11.5	25	56	36.5	39	67.5	3
12	3.2	11.5	26	59	36.5	40	67.5	0
13	0.5	36.5	27	62	36.5	41	70.5	3
14	3.7	36.5	28	65	36.5	42	70.5	0

GENERIC
MARKING DIAGRAM*



FRONTSIDE MARKING



BACKSIDE MARKING

XXXXX = Specific Device Code
AT = Assembly & Test Site Code
YYWW = Year and Work Week Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present. Some products may not follow the Generic Marking.

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